

3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

DATA SHEET UPDATE HISTORY

Version 1.0 – June 4, 2013

Version 1.1 – July 1, 2016

• Forward Voltage updated

Version 1.2 – July 13, 2016

- Added Moisture Sensitivity
- Luminous Intensity updated
- Baking Conditions updated
- Solder Dipping Temperature updated.

Version 1.3 – December 8, 2016

• Operating Temperature Updated



3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

PACKAGE OUTLINES



ITEM	MATERIALS		
Package	Heat-Resistant Polymer (BLACK FACE)		
Encapsulating Resin	Silicone		
Electrodes	Ag Plating Copper Alloy		

NOTES:

1. All dimensions are in millimeters

3.5

2. Electrical Connection between all Cathodes is recommended



3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

ABSOLUTE MAXIMUM RATINGS (Ta=25°C			
Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	70	mA
Peak Pulsed Forward Current	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Power Dissipation	Pd	150	mW
Operating temperature range	Topr	-40~+100	°C
Storage temperature range	Tstg	-40~+100	°C
Solder Dipping Temperature	Tsld	265°C for 10 sec	

Pulse Width≦10 ms, Duty Ratio≦1/10

OPTICAL-ELECTRICAL CHARACTERISTICS

(Ta=25°C)

						-
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Reverse Current	I _R	V _R =5V			50	μA
Forward Voltage	V _F			2.5	3.0	V
Luminous Intensity	Iv	I _F =50mA	1500	2300	3200	Mcd
Luminous Flux	ΦV			7.6		Lm
Dominant Wavelength	λd		585	590	595	Nm
Peak Wavelength	λр			596		Nm
Viewing Angle	20 1/2			120		Deg
Spectral Half Width	Δλ1/2			15		Nm

Note:

Measurement uncertainty of luminous intensity: ±10% Please refer to CIE 1931 chromaticity diagram



3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

LUMINOUS INENSITY BIN TABLE

IF=50mA

Rank Name	Min (mcd)	Max (mcd)
R	1500	1900
S	1900	2500
Т	2500	3200

Tolerance for each bin limit is ±15%

COLOR BIN TABLE

IF=50mA

Rank Name	Min (nm)	Max (nm)
1	585	587.5
2	587.5	590
3	590	592.5
4	592.5	595

Tolerance for each bin limit is ±1nm

VOLTAGE BIN TABLE

$I_F = 50 \text{mA}$

Rank Name	Min (V)	Max (V)
A	2.0	2.1
В	2.1	2.2
С	2.2	2.3
D	2.4	2.4
E	2.4	2.5
F	2.5	2.6

Notes:

- 1. One delivery will include several color ranks and I_V ranks of products. The quantity-ratio of different rank is decided by AOP.
- Bin name typed on the label: IV RANK + Color Rank.
- For example, BIN T2A Means IV: 2500~3200mcd and Color:587.5nm~590nm and VF: 2.0~2.1V 3. AOP has the right to update the information without notice.
- Please double confirm the spec details before placing an order.



3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

TYPICAL ELECTRICAL-OPTICAL CHARACTERISTIC CURVES



Forward Current vs. Forward Voltage



Relative Intensity vs. Forward Current

Forward Current vs. Ambient Temperature

Relative Intensity vs. Wavelength





3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

RADIATION PATTERN



RECOMMENDED SOLDERING PAD PATTERN





3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

SOLDERING CONDITIONS



- Repairing should not be done after the LEDs have been soldered. When repairing is
 unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand
 whether the Characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.



3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

TAPE DIMENSION



TAPE LEADER AND TRAILER DIMENSION





3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

REEL DIMENSION



Note: Baking is required under the following conditions: The pack has been opened for more than 72 hours. Baking recommended conditions: $60 \pm 5^{\circ}C$ for 24 hours



3.5 x 2.7 x 1.9 YELLOW SMD PLCC-4 Black Face

Moisture Sensitivity

AOP's SMD LED are shipped in sealed, moisture-barrier bags (MBB) designed for long shelf life. If SMD LED has exposed with moist environments before soldering, this may cause damage to SMD LED during soldering (reflow) operation.

Storage / Floor Time

Condition	Temperature(C)	Humidity(RH)	Period of Time
Before Open	30	60	1 year from shipping date
After Open	30	60	Within 72 hours

• MSL of this product are MSL4, please seem IPC/JEDEC STD020D for more detail.

• LEDs reach floor time may be damaged while soldering/reflow processing, please baking the LEDs before use.

• If RH indicator card show 60%RH when unseal the package, please bake/discard the LED.

Reseal

- AOP's aluminum MBB may reuse as to reseal the unused LED if MBB has not damaged or had any holes on it.
- Moisture absorbent material (Silica gel) may be reuse if it does not become pink.
- Proper resealed LED's floor time will NOT RESET, only stop counting until open.
- If RH indicator card show 60%RH when open the package, please bake/discard the LED.

Baking

Condition	Temperature(C)	Period of Time
With Reel	60	More than 24 hours, but not more than 48 hours
Without Reel	90	24 hours

• Baking of LED available ONCE only, more than once may damage the LEDs while baking.

• Baking only required when LED reach its floor time.